

**Listing of Claims**

The following listing of claims will replace all prior versions, and listings, of claims in the subject application:

1. (currently amended) A heat-sensitive stencil sheet having a porous resin layer provided on one side of a thermoplastic resin film, and a porous fiber layer bonded by an adhesive to the surface of the porous resin layer, wherein the amount of the adhesive ranges from 0.05 g/m<sup>2</sup> to 1.5 g/m<sup>2</sup>, and the bonding strength between the porous resin layer and the porous fiber layer ranges from 0.8 N/m to 50.0 N/m, wherein the porous resin layer includes a multiplicity of walls and ceilings which define cells.
2. (withdrawn) A heat-sensitive stencil sheet according to claim 1, wherein the adhesive is a primarily urethane adhesive of moisture-curable type.
3. (original) A heat-sensitive stencil sheet according to claim 1 or claim 2, wherein the adhesive is a primarily adhesive of ionizing radiation-curable type.
4. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous resin layer ranges from 0.5 g/m<sup>2</sup> to 10.0 g/m<sup>2</sup> by dry basis.
5. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous resin layer ranges from 1.0 g/m<sup>2</sup> to 5.0 g/m<sup>2</sup> by dry basis.

6. (original) A heat-sensitive stencil sheet according to claim 1, wherein the porous resin layer is a foamy film formed by applying a fluid containing an resin emulsion of water in oil type onto a thermoplastic film and drying it.

7. (original) A heat-sensitive stencil sheet according to claim 1, wherein amount of the porous fiber layer ranges from 1.0 g/m<sup>2</sup> to 15.0 g/m<sup>2</sup>.

8. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous fiber layer ranges from 3.0 g/m<sup>2</sup> to 10.0 g/m<sup>2</sup>.

9. (withdrawn) A method for fabricating a heat-sensitive stencil sheet according to claim 1 comprising the steps of; applying a coating liquid to one side of a thermoplastic film to form a porous resin layer attached to the thermoplastic film; and after at least the outermost surface of the porous resin layer is dried and cured, bonding the porous resin layer to a porous fiber layer coated with a adhesive.

10. (withdrawn) A thermal stencil printing apparatus loaded with a perforated heat-sensitive stencil master produced from a heat-sensitive stencil sheet, wherein the heat-sensitive stencil sheet is one as claimed in claim 1.

Claim 11 (canceled).

12. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein

the porous resin layer has an assembly of cells in a honey combed structure.

13. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein the porous resin layer includes an assembly of granular-shaped or fabric-shaped resin segments coupled together.

14. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous resin layer have an average diameter in a range of 5  $\mu\text{m}$  to 20  $\mu\text{m}$ .

15. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous resin layer are connected in a depth direction and to a lesser degree in a transverse direction, so that sideward deviated penetration of ink in the stencil sheet is decreased.

16. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous fiber layer have an average diameter in a range of 25  $\mu\text{m}$  to 60  $\mu\text{m}$ .

17. (new) A heat-sensitive stencil sheet having a porous resin layer provided on one side of a thermoplastic resin film, and a porous fiber layer bonded by an adhesive to the surface of the porous resin layer, wherein the porous resin layer includes a multiplicity of walls and ceilings which define cells.

18. (new) A heat-sensitive stencil sheet having a porous resin layer provided on one side of a thermoplastic resin film, and a porous fiber layer bonded by an adhesive to the surface of the

porous resin layer, wherein the porous resin layer has an assembly of cells in a honey combed structure.

19. (new) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous fiber layer are connected in a depth direction and to a lesser degree in a transverse direction, so that sideward deviated penetration of ink in the stencil sheet is decreased.